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IGBT

SGP23N60UFD

Ultra-Fast IGBT

General Description

Fairchild's UFD series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UFD series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

Features

- High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.1 \text{ V } @ I_C = 12 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD : t_{rr} = 42ns (typ.)

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Description		SGP23N60UFD	Units
V _{CES}	Collector-Emitter Voltage		600	V
V _{GES}	Gate-Emitter Voltage		± 20	V
	Collector Current	@ T _C = 25°C	23	A
I _C	Collector Current	@ T _C = 100°C	12	A
I _{CM (1)}	Pulsed Collector Current		92	А
I _F	Diode Continuous Forward Current	@ T _C = 100°C	12	Α
I _{FM}	Diode Maximum Forward Current		92	Α
P_{D}	Maximum Power Dissipation	@ T _C = 25°C	100	W
	Maximum Power Dissipation	@ T _C = 100°C	40	W
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C

Notes:(1) Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		1.2	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chai	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
$\Delta B_{VCES}/$ ΔT_J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I_{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	acteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 12mA$, $V_{CE} = V_{GE}$	3.5	4.5	6.5	V
	Collector to Emitter	$I_{C} = 12A$, $V_{GE} = 15V$		2.1	2.6	V
V _{CE(sat)}	Saturation Voltage	$I_{C} = 23A$, $V_{GE} = 15V$		2.6		V
			1			l
•	Characteristics	1		700		~F
C _{ies}	Input Capacitance	$V_{CE} = 30V_{V_{GE}} = 0V_{V_{CE}}$		720		pF
C _{oes}	Output Capacitance Reverse Transfer Capacitance	f = 1MHz		100 25		pF pF
Switchir	ng Characteristics					
t _{d(on)}	Turn-On Delay Time			17		ns
t _r	Rise Time			27		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 12\text{A},$		60	130	ns
t _f	Fall Time	$R_G = 23\Omega, V_{GE} = 15V,$		70	150	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		115		uJ
E _{off}	Turn-Off Switching Loss			135		uJ
E _{ts}	Total Switching Loss			250	400	uJ
t _{d(on)}	Turn-On Delay Time			23		ns
t _r	Rise Time			32		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 12\text{A},$		100	200	ns
t _f	Fall Time	$R_G = 23\Omega, V_{GE} = 15V,$		220	250	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		205		uJ
E _{off}	Turn-Off Switching Loss	7		320		uJ
E _{ts}	Total Switching Loss	1		525	800	uJ
Q _a	Total Gate Charge	V 200 V I 40A		49	80	nC
Qge	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 12\text{A},$		11	17	nC
_ = =	-	V _{GE} = 15V		.		
Q_{gc}	Gate-Collector Charge			14	22	nC

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
)/ Diada Farmard Valta	Diode Forward Voltage	I _E = 12A	$T_C = 25^{\circ}C$		1.4	1.7	V
V_{FM}	Diode Forward Voltage	1 _F = 12A	T _C = 100°C		1.3		V
	t _{rr} Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		42	60	nc
чrr			T _C = 100°C		80		ns
	Diode Peak Reverse Recovery	I _F = 12A,	$T_C = 25^{\circ}C$		3.5	6.0	Α
^I rr	Current	di/dt = 200A/us	T _C = 100°C		5.6		_ A
0	Diada Bayaraa Basayary Chargo		$T_C = 25^{\circ}C$		80	180	nC
Q _{rr} Diode Reverse	Diode Reverse Recovery Charge	everse Recovery Charge	T _C = 100°C		220		TIC

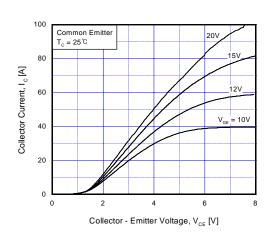


Fig 1. Typical Output Characteristics

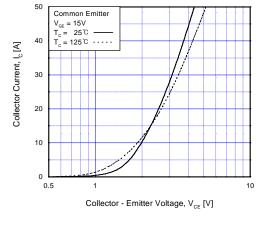


Fig 2. Typical Saturation Voltage Characteristics

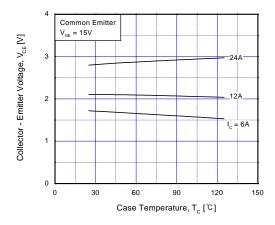


Fig 3. Saturation Voltage vs. Case
Temperature at Variant Current Level

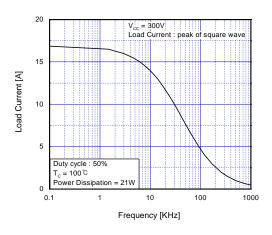


Fig 4. Load Current vs. Frequency

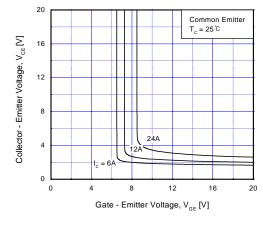


Fig 5. Saturation Voltage vs. V_{GE}

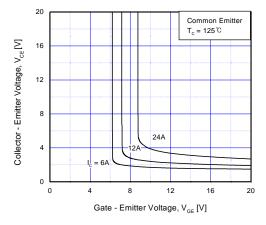
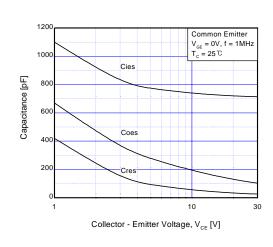


Fig 6. Saturation Voltage vs. $V_{\rm GE}$

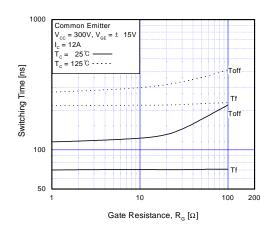
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Common Emitter $V_{CC} = 300V, V_{CE} = \pm 15V$ $I_{C} = 12A$ $I_{C} = 125 \, \text{C}$ $I_{C} = 1$

Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



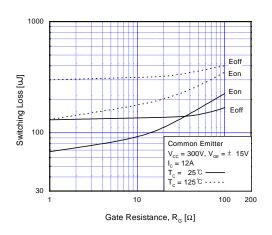
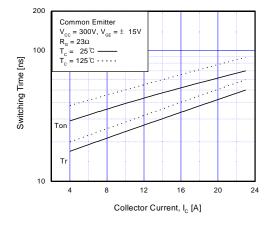


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



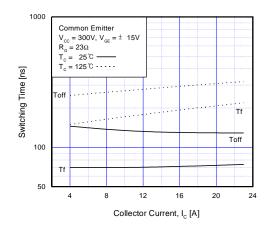
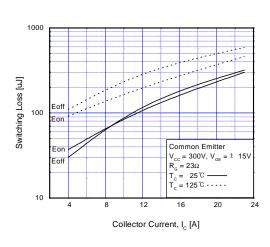


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



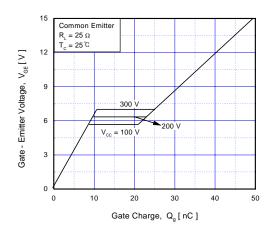
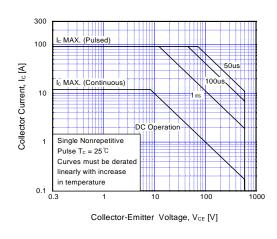


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



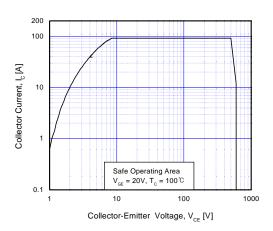


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

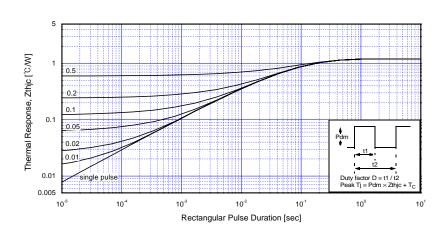
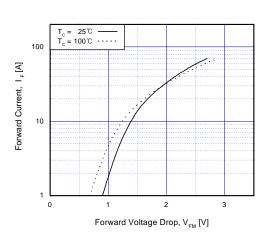


Fig 17. Transient Thermal Impedance of IGBT



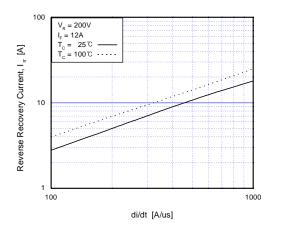
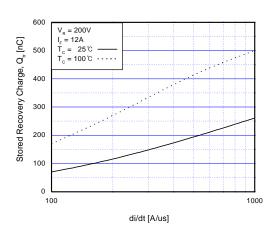


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



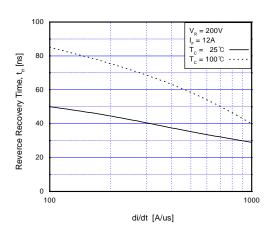
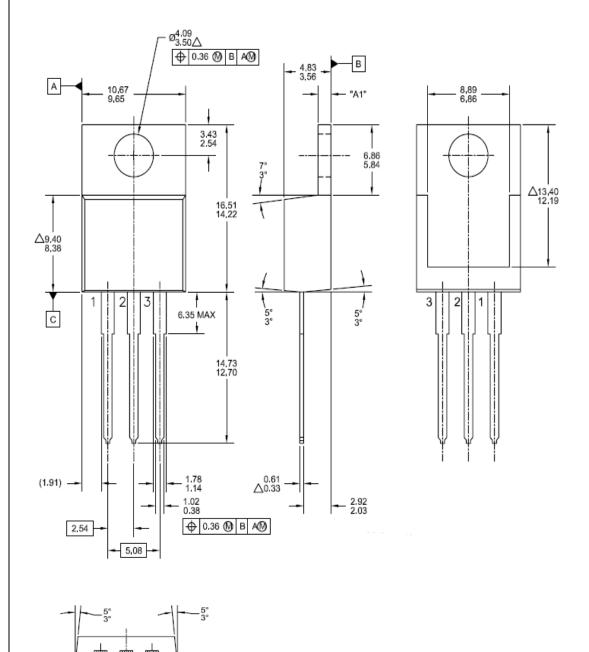


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time

Mechanical Dimensions

TO - 220



Dimensions in Millimeters

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